What is claimed is:

- 1 1. A semiconductor device, comprising:
- 2 a semiconductor chip,
- 3 a chip-mounting substrate which is provided with said
- 4 semiconductor chip mounted on a top surface thereof and first
- 5 conductive pads formed on a bottom surface thereof and connected
- 6 with said semiconductor chip electrically,
- 7 solder balls formed on said first conductive pads,
- 8 a printed circuit board on which second conductive pads
- 9 connected with said solder balls are formed, and
- 10 underfill material injected into a clearance formed
- 11 between said chip-mounting substrate and said printed circuit
- 12 board,
- wherein unevenness is formed on a surface which is brought
- 14 into contact with said underfill material of at least one of
- 15 said chip-mounting substrate and said printed circuit board.
 - 1 2. A semiconductor device according to claim 1, wherein:
 - 2 said unevenness is formed on said first conductive pads
 - 3 or on said second conductive pads selectively.
 - 3. A semiconductor device according to claim 1, wherein:
 - 2 said unevenness is shaped into a slit-like configuration
 - 3 or into a dimple-like configuration.
 - 4. A semiconductor device, comprising:
 - 2 a semiconductor chip,

- 3 a lead frame which is provided with said semiconductor
- 4 chip mounted thereon and electrically connected with said
- 5 semiconductor chip, and
- a printed circuit board including third conductive pads
- 7 which are formed thereon and brought into contact with said lead
- 8 frame,
- 9 wherein at least one of said lead frame and said printed
- 10 circuit board is provided with unevennesses at contact surfaces
- 11 therebetween.
 - 5. A method for fabricating a semiconductor device,
- 2 comprising the steps of:
- 3 forming fourth conductive pads on a bottom surface of a
- 4 chip-mounting substrate,
- forming unevenness on said bottom surface of said
- 6 chip-mounting substrate,
- 7 mounting a semiconductor chip on a top surface of said
- 8 chip-mounting substrate,
- 9 connecting said semiconductor chip with said fourth
- 10 conductive pads electrically,
- forming solder balls on said fourth conductive pads,
- 12 assembling said chip-mounting substrate into a printed
- 13 circuit board by connecting solder balls with fifth conductive
- 14 pads formed on said printed circuit board, and
- injecting underfill material into a clearance formed
- 16 between said chip-mounting substrate and said printed circuit
- 17 board.

- 1 6. A method for fabricating a semiconductor device
- 2 according to claim 5, wherein:
- 3 said step of forming said unevenness on said bottom
- 4 surface of said chip-mounting substrate comprises the step of
- 5 forming unevennesses on said fourth conductive pads
- 6 selectively.
- 7. A method for fabricating a semiconductor device,
- 2 comprising the steps of:
- 3 forming sixth conductive pads on a bottom surface of a
- 4 chip-mounting substrate,
- 5 mounting a semiconductor chip on a top surface of said
- 6 chip-mounting substrate,
- 7 connecting said semiconductor chip with said sixth
- 8 conductive pads electrically,
- 9 forming solder balls on said sixth conductive pads,
- 10 forming unevenness on a surface of a printed circuit board
- 11 on which seventh conductive pads are formed,
- 12 assembling said chip-mounting substrate into said
- 13 printed circuit board by connecting said solder balls with said
- 14 seventh conductive pads formed on said printed circuit board,
- 15 and
- injected underfill material into a clearance formed
- 17 between said chip-mounting substrate and said printed circuit
- 18 board.
- 1 8. A method for fabricating a semiconductor device
- 2 according to claim 7, wherein:

- 3 said step of forming said unevenness on said surface of
- 4 said printed circuit board comprises the step of forming
- 5 unevennesses on said seventh conductive pads selectively.
- 9. A method for fabricating a semiconductor device,
- 2 comprising the steps of:
- 3 forming eighth conductive pads on a bottom surface of a
- 4 chip-mounting substrate,
- forming a first unevenness on a bottom surface of said
- 6 chip-mounting substrate,
- 7 mounting a semiconductor chip on a top surface of said
- 8 chip-mounting substrate,
- 9 connecting said semiconductor chip with said eighth
- 10 conductive pads electrically,
- 11 forming solder balls on said eighth conductive pads,
- 12 forming a second unevenness on a surface of a printed
- 13 circuit board on which ninth conductive pads are formed,
- 14 assembling said chip-mounting substrate into said
- 15 printed circuit board by connecting said solder balls with said
- 16 ninth conductive pads, and
- injecting underfill material into a clearance formed
- 18 between said chip-mooting substrate and said printed circuit
- 19 board.
- 1 10. A method for fabricating a semiconductor device
- 2 according to claim 9, wherein:
- 3 said step of forming said first unevenness comprises the
- 4 step of forming unevennesses on surfaces of said eighth

- 5 conductive pads selectively, and
- 6 said step of forming said second unevenness comprises the
- 7 step of forming unevennesses on surfaces of said ninth
- 8 conductive pads selectively.
- 1 11. A method for fabricating a semiconductor device,
- 2 comprising the steps of:
- 3 forming unevennesses on predetermined parts of a lead
- 4 frame,
- 5 mounting a semiconductor chip on said lead frame,
- 6 connecting said semiconductor chip with said lead frame
- 7 electrically, and
- 8 assembling said lead frame on which said semiconductor
- 9 chip is mounted into a printed circuit board by bringing said
- 10 unevennesses formed on said lead frame into contact with tenth
- 11 conductive pads formed on said printed circuit board.
- 1 12. A method for fabricating a semiconductor device,
- 2 comprising the steps of:
- 3 mounting a semiconductor chip on a lead frame,
- 4 forming unevennesses on surfaces of eleventh conductive
- 5 pads formed on a printed circuit board, and
- 6 assembling said lead frame on which said semiconductor
- 7 chip is mounted into said printed circuit board by connecting
- 8 said lead frame with said eleventh conductive pads on which said
- 9 unevennesses are formed.
- 1 13. A method for fabricating a semiconductor device,

- 2 comprising the steps of:
- 3 forming first unevennesses on predetermined parts of a
- 4 lead frame,
- 5 mounting a semiconductor chip on said lead frame,
- 6 connecting said semiconductor chip with said lead frame
- 7 electrically,
- 8 forming second unevennesses on surfaces of twelfth
- 9 conductive pads formed on a printed circuit board, and
- 10 assembling said lead frame on which said semiconductor
- 11 chip is mounted into said printed circuit board by bringing said
- 12 first unevennesses formed on said lead frame into contact with
- 13 said second unevennesses formed on said twelfth conductive
- 14 pads.